

Small switching (30V, 0.1A)

• Features

- Low on-resistance.
- Fast switching speed.
- Low voltage drive (2.5V) makes this device ideal for portable equipment.
- Easily designed drive circuits.
- Easy to parallel.

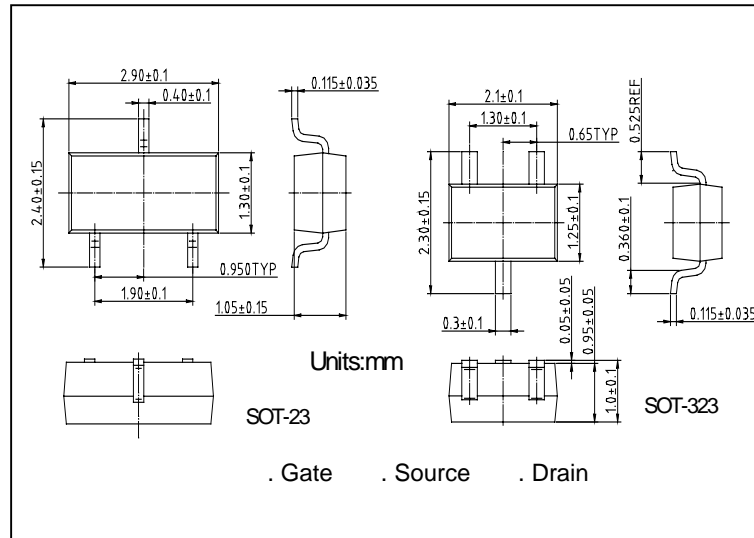
• Applications

Interfacing, switching (30V, 100mA)

• Structure

Silicon N-channel MOSFET

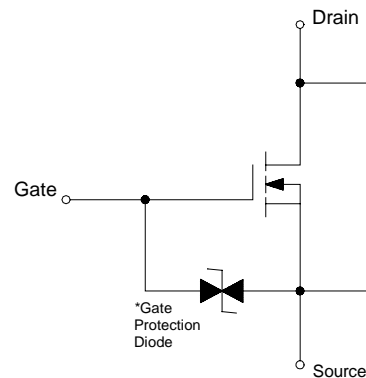
• External dimensions



• Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Rated	Units
Drain-source voltage	V_{DSS}	30	V
Gate-source voltage	V_{GSS}	± 20	V
Drain current	Continuous	I_D	100 mA
	Pulsed	I_{DP}	200 mA
Reverse drain current	Continuous	I_{DR}	100 mA
	Pulsed	I_{DRP}	200 mA
Total power dissipation	P_D	200	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55~+150	°C

• Equivalent circuit



• Electrical Characteristics (Ta = 25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Gate-source leakage	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	----	----	±1	μA
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D=10\mu A, V_{GS}=0V$	30	----	----	V
Zero gate voltage drain current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V$	----	----	1	μA
Gate threshold Voltage	$V_{GS(th)}$	$V_{DS}=3V, I_D=100\mu A$	0.8	----	1.5	V
Static drain-source on-state resistance	$R_{DS(ON)}$	$I_D=10mA, V_{GS}=4V$	----	5	8	
	$R_{DS(ON)}$	$I_D=1mA, V_{GS}=2.5V$	----	7	13	
Forward transfer admittance	Y_{fs}	$V_{DS}=3V, I_D=10mA$	20	----	----	mS
Input capacitance	C_{iss}	$V_{DS}=5V$	----	13	----	pF
Output capacitance	C_{oss}	$V_{GS}=0V$	----	9	----	pF
Reverse transfer capacitance	C_{rss}	F=1 MHz	----	4	----	pF

Turn-on delay time	$t_d(\text{on})$	$I_D=10\text{ mA}, V_{DO}=5\text{V}$ $V_{GS}=5\text{V}$ $R_L=500$ $R_{GS}=10$	----	15	----	ns
Rise time	t_r		----	35	----	ns
Turn-off delay time	$t_d(\text{off})$		----	80	----	ns
Fall time	t_f		----	80	----	ns

● Typical Performance Characteristics

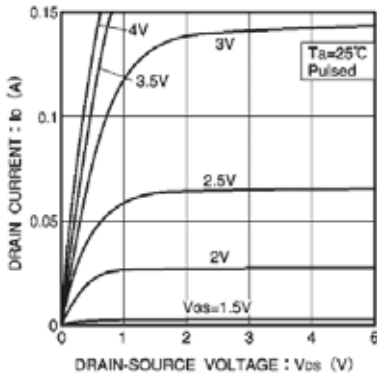


Fig.1 Typical output characteristics

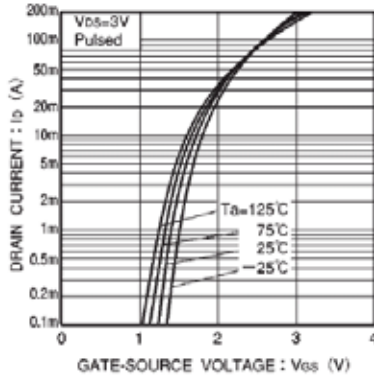


Fig.2 Typical transfer characteristics

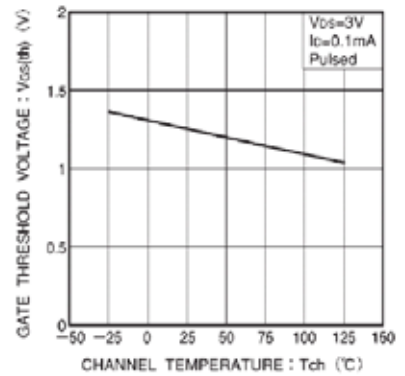


Fig.3 Gate threshold voltage vs. channel temperature

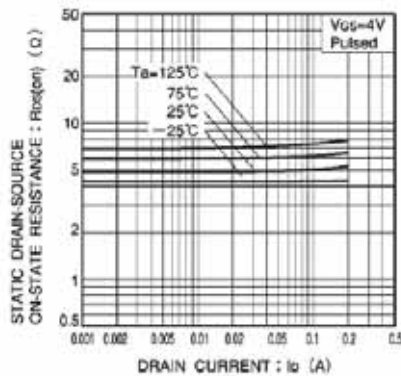


Fig.4 Static drain-source on-state resistance vs. drain current (I)

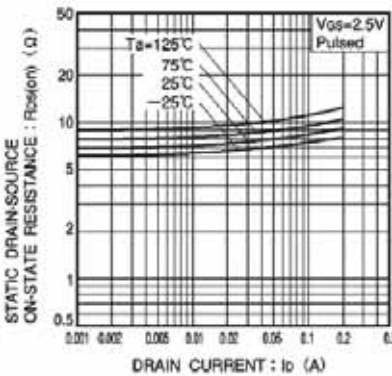


Fig.5 Static drain-source on-state resistance vs. drain current (II)

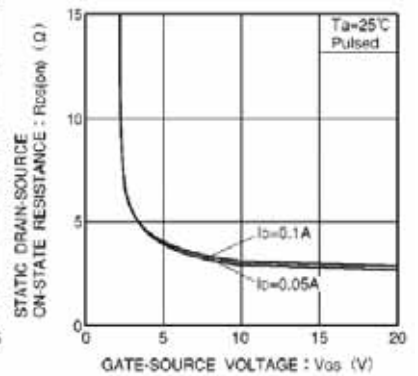


Fig.6 Static drain-source on-state resistance vs. gate-source voltage

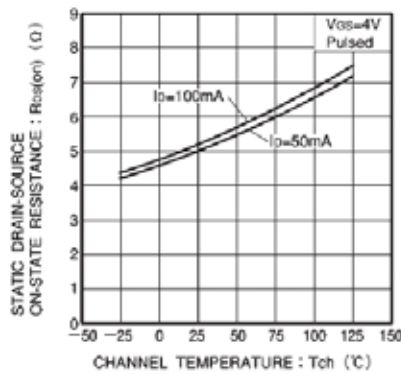


Fig.7 Static drain-source on-state resistance vs. channel temperature

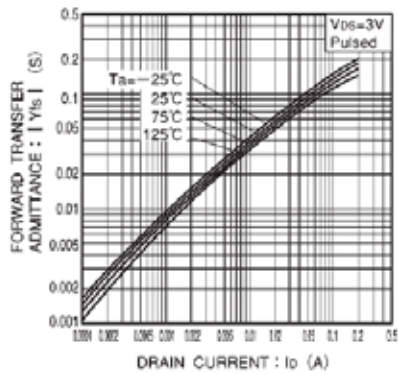


Fig.8 Forward transfer admittance vs. drain current

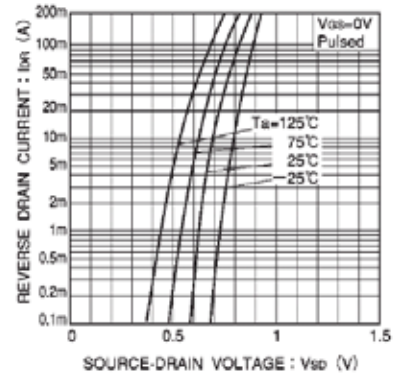


Fig.9 Reverse drain current vs. source-drain voltage (I)